

Tin-Lead

SLOTOLET G 30 1

Tin-Lead SLOTOLET G 30 1 is a fluoride and formaldehyde-free process for the deposition of bright tin-lead coatings with a lead content of up to 40 % of lead. The electrolyte is mainly applied in the field of electronic components finishing and can be used for both rack- and barrel applications.

Solderability of the coatings is excellent even after accelerated heat ageing (e.g. tempering 16 h/155 °C).

The additives required for make-up and operation don't contain any alkylphenol ethoxylates (nonylphenol ethoxylates).

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instructions carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

